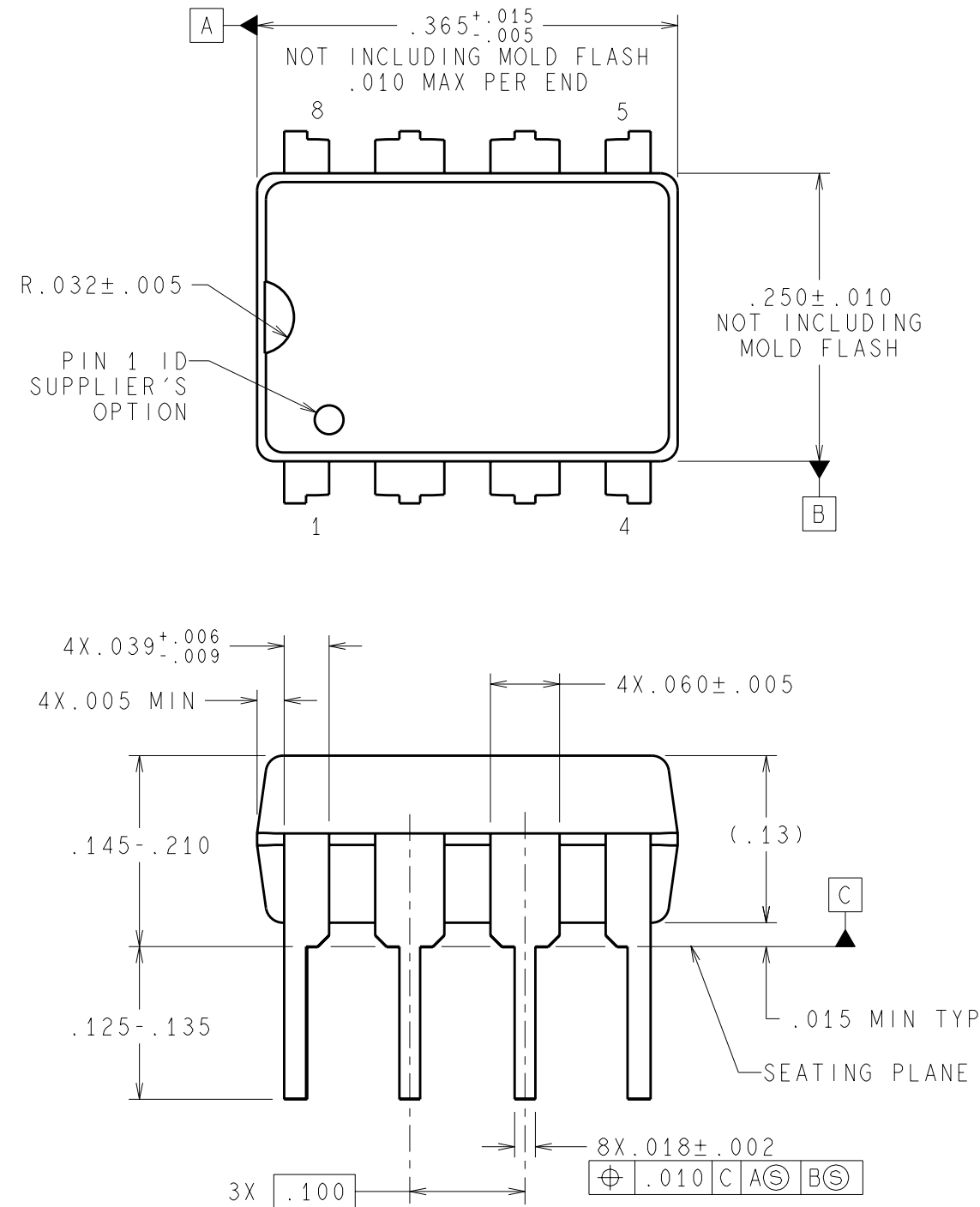


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
G	UPDATE DWG PER CURRENT STANDARDS & NOTES; REDRAW ON PRO/E & REVISE TITLE.	2033	05/16/2006	MS/KS



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SELECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION MS-001, VARIATION BA.

DIMENSIONS ARE IN INCHES
DIMENSIONS IN () FOR REFERENCE ONLY

APPROVALS	DATE	National Semiconductor		
DRAWN MARTA SUCHY	05/16/2006	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG	05/16/2006	MDIP, .365x.250x.130in, 8 LEAD, .100in PITCH		
ENGR. CHK. KURT SINCERBOX	05/16/2006			
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		NTS	B	(SC)MKT-N08E
FORMERLY: N/A		SHEET 1 of 1		REV G